

ABSTRACT OF THE DISCLOSURE

An electronic package of the kind having a folded substrate is provided. The substrate is configured so that a stress concentration is created where folding is desired. In the present example, the stress concentration is created with first a resilient metal ground layer that resists bending and has an edge that promotes the creation of a stress concentration in a flexible layer at or near the edge. A second metal ground layer resists bending in another portion of the substrate, and also has an edge creating a stress concentration in a different area of the flexible layer. The portions of the substrate having the first and second resilient metal ground layers can be folded over one another with substantially no bending in these portions, while a fold portion between the edges bends to allow for folding of the substrate.